



2.0Amp. Surface Mount Schottky Barrier Diodes

SK2XSA Series

Features

- For surface mounted applications.
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications
- Plastic material used carries Underwriters Laboratory Flammability Classification 94V-0
- Low leakage current
- High surge capability
- High temperature soldering: 250°C/10 seconds at terminals
- Exceeds environmental standards of MIL-S-19500/228
- Pb-free package

Mechanical Data

- Case: SMA/DO-214AC molded plastic.
- Terminals: Solder plated, solderable per MIL-STD-750 method 2026
- Polarity: Indicated by cathode band.
- Packaging: 12mm tape per EIA STD RS-481.
- Weight: 0.064 gram, 0.002 ounce

Maximum Ratings and Electrical Characteristics

(Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.)

Parameter	Symbol	Type					Units
		SK22	SK24	SK26	SK28	SK2B	
Repetitive peak reverse voltage	V _{RRM}	20	40	60	80	100	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	V
Maximum DC blocking voltage	V _R	20	40	60	80	100	V
Maximum instantaneous forward voltage, I _F =2A	V _F	0.5		0.7	0.85		V
Maximum average forward rectified current @ T _L = 100°C	I _O	2.0					A
Peak forward surge current @8.3ms single half sine wave superimposed on rated load (JEDEC method)	I _{FSM}	50					A
Maximum DC reverse current @ T _J = 25°C At Rated DC Blocking Voltage @ T _J = 100°C	I _R	0.5 10					mA mA
Maximum thermal resistance, Junction to ambient(Note 1)	R _{th,JA}	88 (typ)					°C/W
Diode junction capacitance @ f = 1MHz and applied 4V reverse voltage	C _J	110 (typ)					pF
Operating Junction and Storage temperature Rang	T _J , T _{stg}	-55 ~ +125 / -55 ~ +150					°C

Notes : .Mounted on PCB with 14mm² (0.013mm thickness) copper pad area.

Characteristic Curves

FIG.1 - FORWARD CURRENT DERATING CURVE

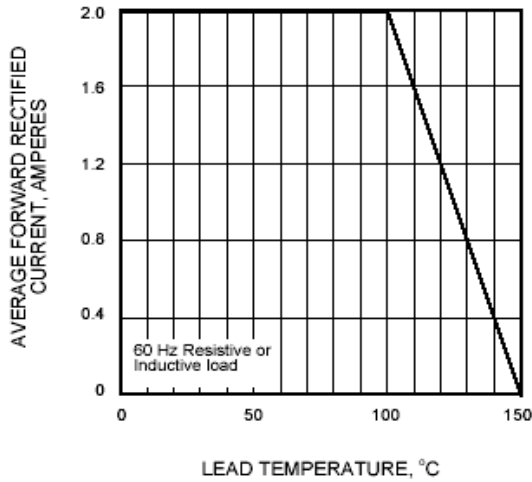


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

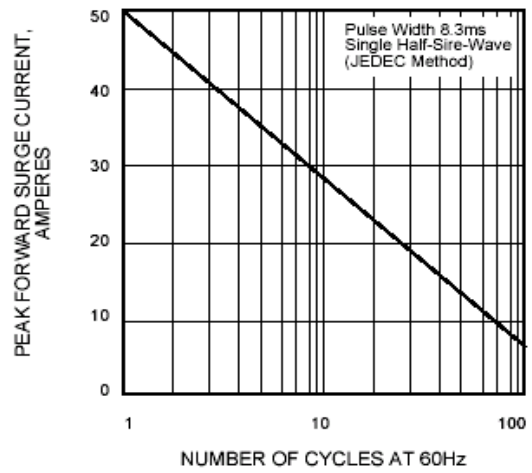


FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

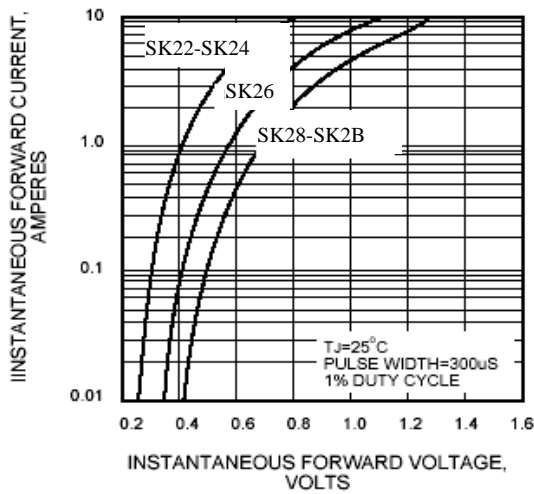


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

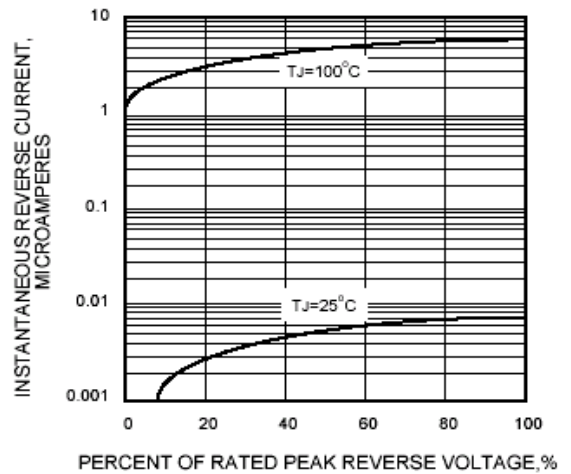
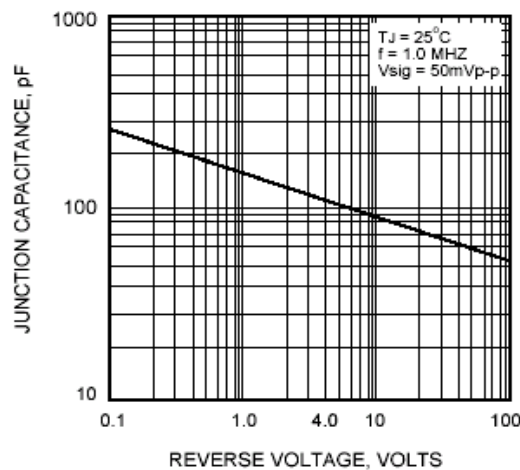
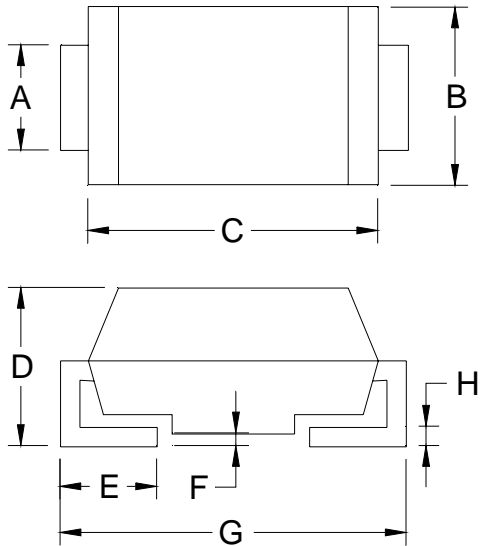


FIG.5 - TYPICAL JUNCTION CAPACITANCE



SMA Dimension



The diagram shows two views of the SMA package. The top view is a side profile with dimensions A (lead height), B (package height), and C (package length). The bottom view is a top-down perspective with dimensions D (lead length), E (lead width), F (lead thickness), G (package width), and H (lead thickness).

Marking :

Device	SK22	SK24	SK26	SK28
Code	SK22	SK24	SK26	SK28

Device	SK2B			
Code	SK2B			

SMA/DO-214AC Plastic
 Surface Mounted Package
 CYStek Package Code : SA

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.055	0.062	1.40	1.60	E	0.030	0.060	0.76	1.52
B	0.098	0.114	2.50	2.90	F	0.002	0.008	0.051	0.203
C	0.157	0.181	4.00	4.60	G	0.188	0.208	4.80	5.28
D	0.078	0.096	2.00	2.44	H	0.006	0.012	0.152	0.305

Notes : 1. Controlling dimension : millimeters.

2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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